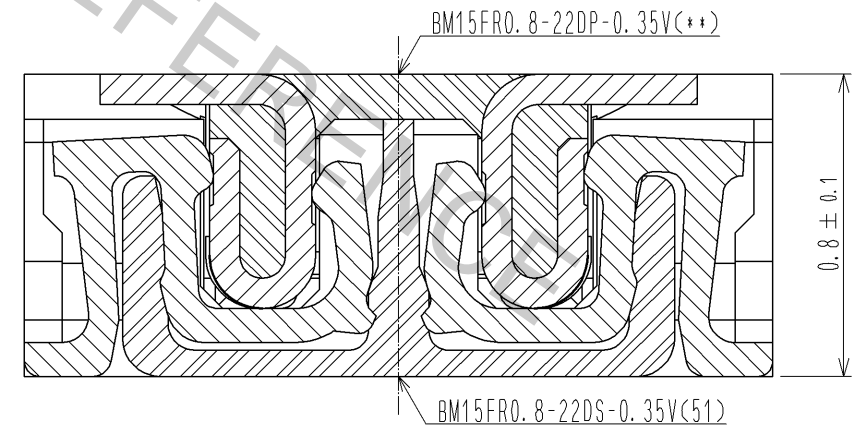


ENGAGEMENT FIGURE (50:1)



NOTE) 1 . ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX  
 2 CONTACT PLATING SPECIFICATIONS.  
 CONTACT AREA : GOLD 0.05 μm MIN  
 SMT LEAD : GOLD 0.05 μm MIN  
 UNDERPLATING : NICKEL 1 μm MIN  
 ( SURFACE : SEALING )  
 3 REINFORCED METAL FITTINGS LOCK  
 SMT LEAD : GOLD 0.05 μm MIN  
 UNDERPLATING : NICKEL 1 μm MIN  
 ( SURFACE : SEALING )  
 4 CAV NO. AND HRS MARK MAY BE INDICATED IN APPROX POSITION SHOWN.

NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
4	PS	CLEAR (ENBOSSED CARRIER TAPE)	7	PS	CLEAR (REINFORCEMENT COLLAR)
3	PHOSPHOR BRONZE	3	6	PS	BLACK (PLASTIC REEL)
2	PHOSPHOR BRONZE	2	5	POLYESTER	CLEAR (COVER TAPE)
1	LCP	UL94 V-0, BLACK			

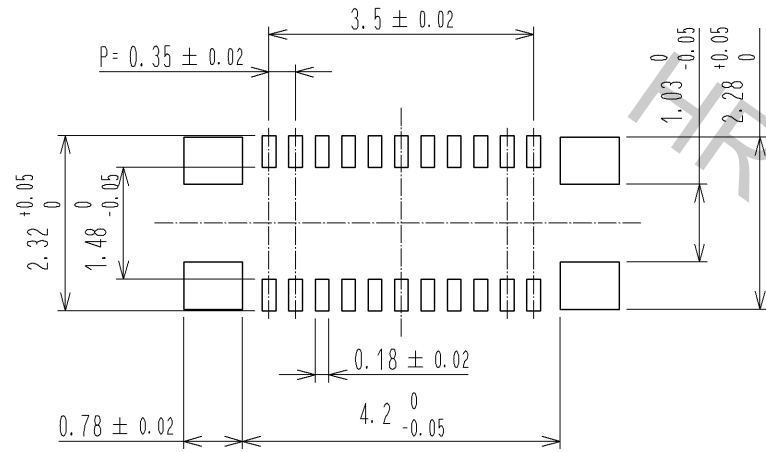
  

UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	10:1	△	APPROVED : KH. IKEDA 13.12.05			
			CHECKED : YH. MICHIDA 13.12.05			
			DESIGNED : YK. KOBAYASHI 13.12.02			
			DRAWN : YK. KOBAYASHI 13.12.02			

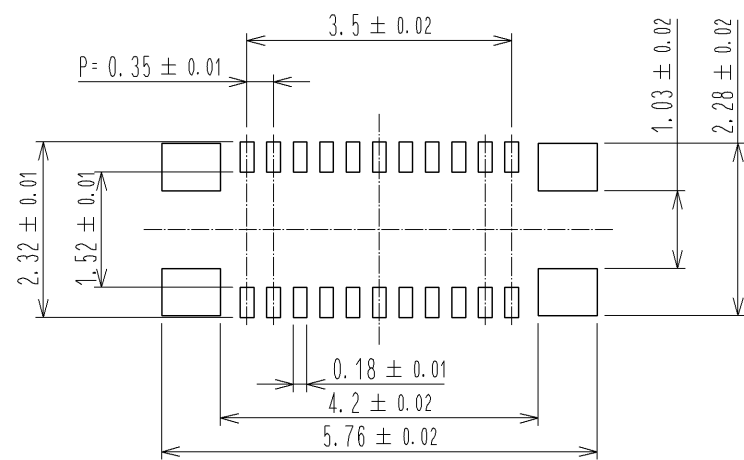
DRAWING NO.	EDC3-352577-01
PART NO.	BM15FR0.8-22DS-0.35V(51)
CODE NO.	CL673-1220-1-51

◆ RECOMMENDED PCB LAYOUT

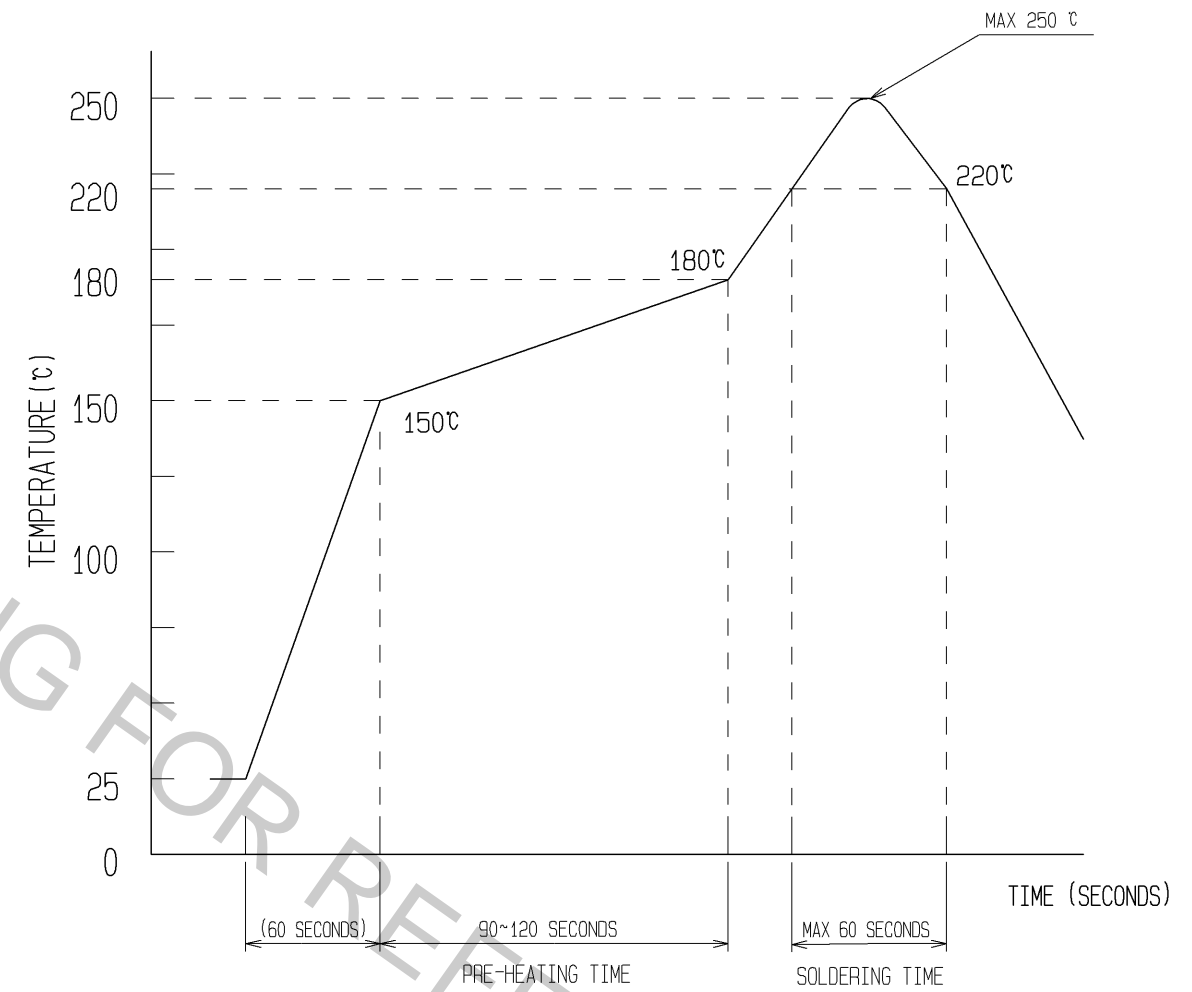


◆ RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : 100 μm



5 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



- REFLOW METHOD: IR REFLOW  
 NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.  
 1) REFLOW TIME  
 DURATION ABOVE 220°C, 60 SEC. MAX.  
 (PEAK TEMPERATURE: 250°C MAX)  
 2) PRE-HEAT TIME  
 PRE-HEAT TEMPERATURE(MIN): 150°C  
 PRE-HEAT TEMPERATURE(MAX): 180°C  
 PRE-HEAT TIME: 90-120 sec.

5 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

<b>HRS</b>	DRAWING NO.	EDC3-352577-01
	PART NO.	BM15FR0.8-22DS-0.35V<51>
	CODE NO.	CL673-1220-1-51

